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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Susan J. Boon

Title: METHOD OF PACKAGING AT A WAFER LEVEL

Docket No.: 303.601US3

Filed: November 26, 2003

Examiner: James M. Mitchell

Serial No.: 10/722,838

Due Date: February 7, 2005

Group Art Unit: 2814

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

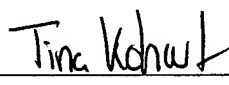
- ☒ A return postcard.
- ☒ A Response to Restriction Requirement (1 Page).
- ☒ A Communication Concerning Related Applications (1 pg.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: 
Atty: David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of February, 2005.



Name



Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/722,838

PATENT

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COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/723474	November 26, 2003	303.601US2	ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING

Respectfully submitted,

SUAN J. BOON

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date

7 February 2005

By

David R. Cochran
Reg. No. 46,632

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Name

Tina Kohut

Signature

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